# CRMKTL1024A

## **Description**

### **N-channel Enhancement Mode Power MOSFET**

#### **Features**

• 100V, 40A

 $R_{DS(ON)}$  Typ = 17m $\Omega$  @  $V_{GS}$  = 10V  $R_{DS(ON)}$  Typ = 18m $\Omega$  @  $V_{GS}$  = 4.5V

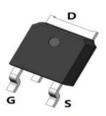
- Advanced Trench Technology
- Excellent R<sub>DS(ON)</sub> and Low Gate Charge

#### **Applications**

- Load Switch
- PWM Application
- Power Management

100% UIS TESTED! 100% ΔVds TESTED!

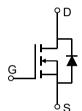








**Marking and Pin Assignment** 



**Schematic Diagram** 

#### **Package Marking and Ordering Information**

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
CRMKTL1024A	CRMKTL1024A	TAPING	TO-252-3L	13"	2500	25000

#### Absolute Maximum Ratings (@ T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units	
V <sub>DS</sub>	Drain-to-Source Voltage		100	V	
V <sub>GS</sub>	Gate-to-Source Voltage		±20	V	
I <sub>D</sub>	Cantinuana Busin Comment	T <sub>C</sub> = 25°C	40	А	
	Continuous Drain Current	T <sub>C</sub> = 100°C	24		
I <sub>DM</sub>	Pulsed Drain Current (1)		160	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)		121	mJ	
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C	62.5	W	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		2	°C/W	
T <sub>J</sub> , T <sub>STG</sub>	Junction & Storage Temperature Range		-55 to 150	°C	



# CRMKTL1024A

#### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	1	±100	nA
On Cha	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.7	2.5	V
	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	17.0	22.0	mΩ
$R_{DS(ON)}$		$V_{GS} = 4.5V, I_{D} = 10A$	-	18.0	24.0	mΩ
Dynami	ic Characteristics					
C <sub>iss</sub>	Input Capacitance		- (	5060	-	pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V,$		175	_	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1MHz	-	155	-	pF
$Q_g$	Total Gate Charge			101	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_D = 20A$	<u> </u>	26	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	- V <sub>DS</sub> - 30V, I <sub>D</sub> - 20A	-	24	-	nC
Switchi	ing Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime	4()	-	20	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	24	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 20A, R_{GEN} = 2.5\Omega$	-	45	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	15	-	ns
Drain-S	Source Diode Characteristics and I	Max Ratings				
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	40	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	160	А
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 454 31/34 4000	-	40	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 15A$ , di/dt = 100A/us	-	63	-	nC

Notes:

<sup>1.</sup> Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

<sup>2.</sup>  $E_{AS}$  condition: Starting  $T_J$ =25°C,  $V_{DD}$ =50V,  $V_G$ =10V,  $R_G$ =25ohm, L=0.5mH,  $I_{AS}$ =22A

<sup>3.</sup> Pulse Test: Pulse Width  $\!\!\!<\!300\mu s,$  Duty Cycle  $\!\!\!<\!0.5\%.$ 



## **Test Circuit**

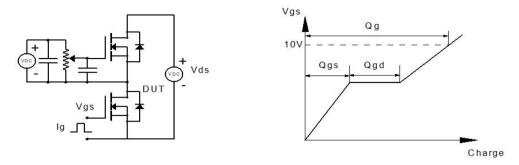


Figure 1: Gate Charge Test Circuit & Waveform

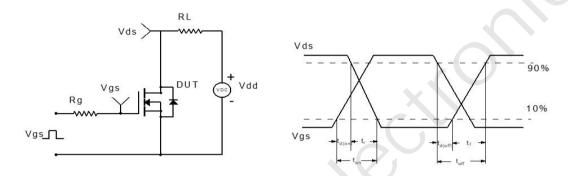


Figure 2: Resistive Switching Test Circuit & Waveform

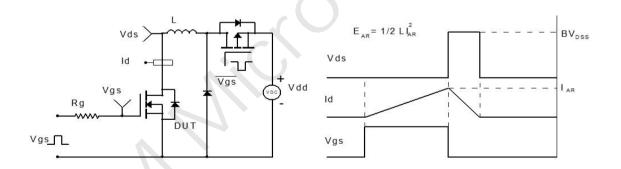


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

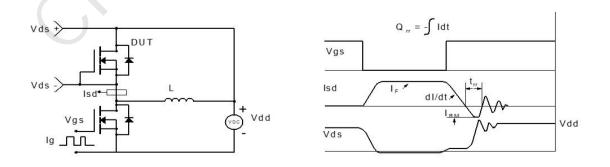
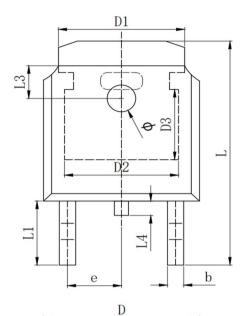


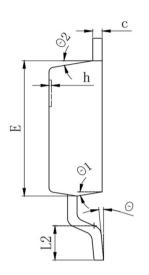
Figure 4: Diode Recovery Test Circuit & Waveform



# CRMKTL1024A

# Package Mechanical Data(TO-252-3L)





SYMBOL	MILLIMETER				
	MIN	Тур.	MAX		
A	2. 200	2.300	2.400		
A1	0.000		0.127		
b	0. 640	0.690	0.740		
c(电镀后)	0.460	0.520	0.580		
D	6. 500	00 6.600 6.700			
D1	5.334 REF				
D2	4. 826 REF				
D3	3. 166 REF				
E	6.000	6. 100	6.200		
e	2. 286 TYP				
h	0.000	0.100	0.200		
L	9. 900	10.100	10.300		
L1	2. 888 REF				
L2	1. 400	1.550	1.700		
L3	1. 600 REF				
L4	0. 600	0.800	1.000		
ф	1. 100	1.200	1.300		
θ	0°		8°		
θ 1	9° TYP				
θ 2	9° TYP				



Information furnished in this document is believed to be accurate and reliable. However, CRM Microelectronics Co. , Ltd assumes no responsibility for the consequences of use without consideration for such information nor use beyond it.

Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, CRM complies with the agreement.

Products and information provided in this document have no infringement of patents. CRM assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information.

is a registered trademark of CRM Microelectronics Co., Ltd. Copyright ©2023 CRM Microelectronics Co., Ltd. Printed All rights reserved.